

cont.  
A1 formed by laser beam machining, etc., and the conductive layer 3 can also be slit by post-treatment processes to form the notch parts. If post-treatment processes are used to form the notch parts, a part is actually mounted on a--.

Page 14, lines 26-27, change "to the board main body 2 all in the thickness direction"

to -in the thickness direction to the board main body 2--.

A2  
IN THE CLAIMS

Please cancel Claims 1-3 without prejudice or disclaimer.

Please add the following new claims:

sub. B1  
--7. A circuit board for mounting a part having a plurality of bumps by ultrasonic bonding, said circuit board comprising:  
a main body; and  
a conductive layer provided on said main body, said conductive layer having a conductive pattern, said conductive pattern having at least one bonding area configured to correspond to the plurality of bumps of the part, said conductive layer having one of an isolated notch part and recess located proximate said at least one bonding area, wherein said notch part or said recess is configured to extend in a direction traverse to an ultrasonic vibrating direction of the ultrasonic bonding.

A3  
8. The circuit board as claimed in claim 7, wherein said notch part or said recess partially narrows said conductive pattern to form a narrow pattern part.

sub. B2  
9. The circuit board as claimed in claim 7, wherein said notch part or said recess narrows said conductive pattern at said at least one bonding area.

10. A method of mounting a part having a plurality of bumps on a circuit board by ultrasonic bonding, said method comprising the steps of: